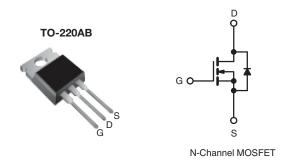


Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	100			
R _{DS(on)} (Ω)	V _{GS} = 5.0 V 0.54			
Q _g (Max.) (nC)	6.1			
Q _{gs} (nC)	2.6			
Q _{gd} (nC)	3.3			
Configuration	Single			



FEATURES

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- Logic-Level Gate Drive
- R_{DS(on)} Specified at V_{GS} = 4 V and 5 V
- 175 °C Operating Temperature
- Fast Switching
- · Ease of Paralleling
- Compliant to RoHS Directive 2002/95/EC

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRL510PbF		
Lead (FD)-life	SiHL510-E3		
SnPb	IRL510		
JIII D	SiHL510		

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	100	V	
Gate-Source Voltage			V_{GS}	± 10	, v	
Continuous Drain Current	V _{GS} at 5 V	T _C = 25 °C		5.6		
Continuous Drain Current		T _C = 100 °C	I _D	4.0	Α	
Pulsed Drain Current ^a		I _{DM}	18			
Linear Derating Factor				0.29	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	100	mJ	
Repetitive Avalanche Current ^a			I _{AR}	5.6	Α	
Repetitive Avalanche Energy ^a			E _{AR}	4.3	mJ	
Maximum Power Dissipation $T_C = 25 ^{\circ}C$			P_{D}	43	W	
Peak Diode Recovery dV/dtc			dV/dt	5.5	V/ns	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 175	°C		
Soldering Recommendations (Peak Temperature) for 10 s						300 ^d
Mounting Toyaus	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque				1.1	N⋅m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. V_{DD} = 25 V, starting T_J = 25 °C, L = 4.8 mH, R_g = 25 Ω , I_{AS} = 5.6 A (see fig. 12).
- c. $I_{SD} \le 5.6 \text{ A}$, $dI/dt \le 75 \text{ A/}\mu\text{s}$, $V_{DD} \le V_{DS}$, $T_{J} \le 175 \text{ °C}$.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62		
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50	-	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	3.5		

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	100	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.12	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	1.0	-	2.0	V
Gate-Source Leakage	I _{GSS}	,	V _{GS} = ± 10 V	-	-	± 100	nA
Zava Cata Valtaga Dvain Cuvvant	I _{DSS}	V _{DS} =	V _{DS} = 100 V, V _{GS} = 0 V		-	25	μА
Zero Gate Voltage Drain Current		$V_{DS} = 80 \text{ V},$	V _{DS} = 80 V, V _{GS} = 0 V, T _J = 150 °C		-	250	
Drain Source On State Begintance	В	V _{GS} = 5.0 V	I _D = 3.4 A ^b	-	-	0.54	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 4.0 V	I _D = 2.8 A ^b	-	-	0.76	Ω
Forward Transconductance	9 _{fs}	V _{DS} =	= 50 V, I _D = 3.4 A ^b	1.9	-	-	S
Dynamic							
Input Capacitance	C _{iss}		V _{GS} = 0 V,	-	250	-	
Output Capacitance	C _{oss}	$V_{DS} = 0 V$, $V_{DS} = 25 V$,		-	80	-	рF
Reverse Transfer Capacitance	C _{rss}	f = 1.	.0 MHz, see fig. 5	-	15	-	
Total Gate Charge	Qg			-	-	6.1	
Gate-Source Charge	Q _{gs}	V _{GS} = 5.0 V	$I_D = 5.6 \text{ A}, V_{DS} = 80 \text{ V}$ see fig. 6 and 13 ^b	-	-	2.6	nC
Gate-Drain Charge	Q _{gd}	1	See lig. 6 and 16	-	-	3.3	
Turn-On Delay Time	t _{d(on)}			-	9.3	-	
Rise Time	t _r	V _{DD} = 50 V, I _D = 5.6 A - 47		-]		
Turn-Off Delay Time	t _{d(off)}	- 9.3 V _{DD} = 50 V, I _D = 5.6 A - 47		-	ns		
Fall Time	t _f	See lig. 10-		-	18	-	1
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from		-	4.5	-	ъЦ
Internal Source Inductance	L _S	package and die contact	center of	-	7.5	-	nH
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the		-	-	5.6	A
Pulsed Diode Forward Current ^a	I _{SM}		integral reverse p - n junction diode		-	18	
Body Diode Voltage	V_{SD}	T _J = 25 °C	I_{S} , I_{S} = 5.6 A, V_{GS} = 0 V^{b}	-	-	2.5	V
Body Diode Reverse Recovery Time	t _{rr}	T. =	25 °C, I _F = 5.6 A,	-	110	130	ns
Body Diode Reverse Recovery Charge	Q _{rr}		$dt = 100 \text{ A/}\mu\text{s}^{\text{b}}$	-	0.50	0.65	μC
· · · · · ·		Intrinsic turn-on time is negligible (turn-on is dominated by L _S and					

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

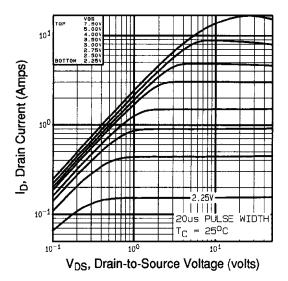


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

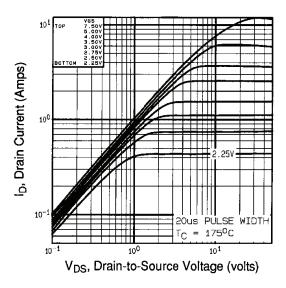


Fig. 2 - Typical Output Characteristics, T_C = 175 °C

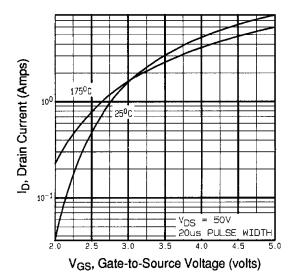


Fig. 3 - Typical Transfer Characteristics

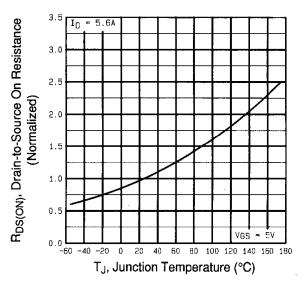


Fig. 4 - Normalized On-Resistance vs. Temperature



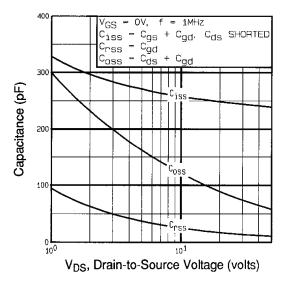


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

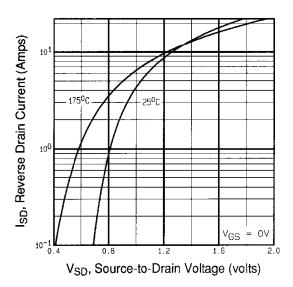


Fig. 7 - Typical Source-Drain Diode Forward Voltage

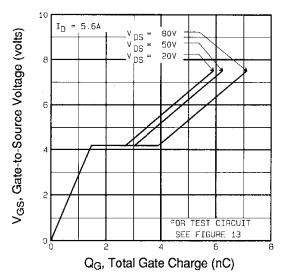


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

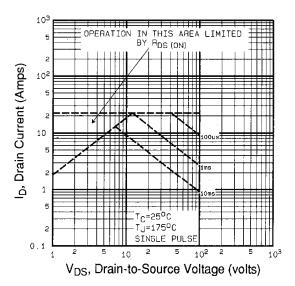


Fig. 8 - Maximum Safe Operating Area





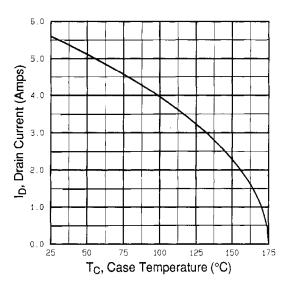


Fig. 9 - Maximum Drain Current vs. Case Temperature

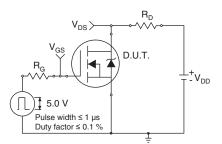


Fig. 10a - Switching Time Test Circuit

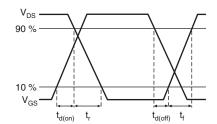


Fig. 10b - Switching Time Waveforms

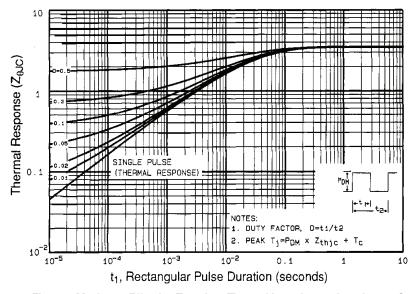


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



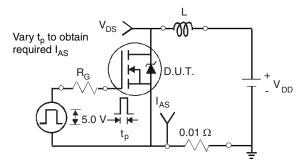


Fig. 12a - Unclamped Inductive Test Circuit

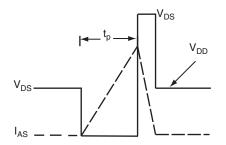


Fig. 12b - Unclamped Inductive Waveforms

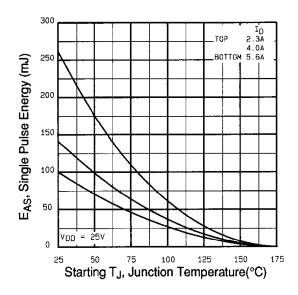


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

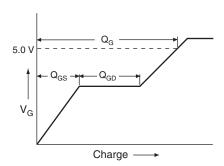


Fig. 13a - Basic Gate Charge Waveform

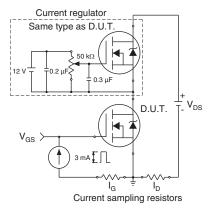
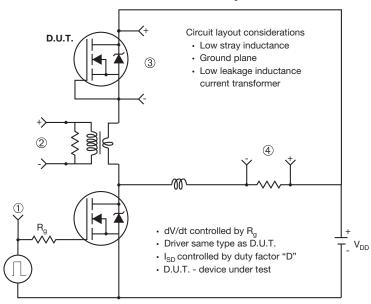


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



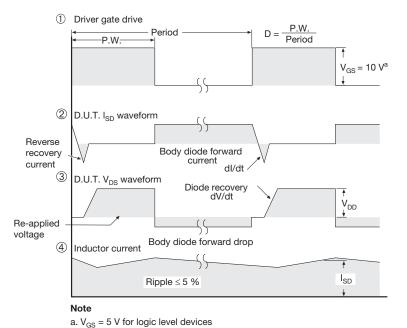


Fig. 14 - For N-Channel

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TO-220-1



DIM.	MILLIN	METERS	INCHES		
DIIVI.	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	

Note

 \bullet $M^{\star}=0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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